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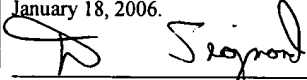
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Chuen Rong Leu et al.
Assignee: Bridge Semiconductor Corporation
Title: SEMICONDUCTOR CHIP ASSEMBLY WITH EMBEDDED METAL PILLAR
Serial No.: 10/714,794 Filed: November 17, 2003
Examiner: Williams, A. Group Art Unit: 2826
Atty. Docket No.: BDG024

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313

TRANSMITTAL OF FORMAL DRAWINGS

Attached please find the formal drawings (36 sheets) for this application.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on January 18, 2006.	
	<u>1, 18, 06</u>
David M. Sigmond Attorney for Applicant	Date of Signature

Respectfully submitted,



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